

INFORMATION DISCLOSURE STATEMENT BY APPLICANT <i>(Not for submission under 37 CFR 1.99)</i>	Application Number		10644718	
	Filing Date		2003-08-20	
	First Named Inventor		Yi-Hsun Wu et al.	
	Art Unit		2836	
	Examiner Name		Danny Nguyen	
	Attorney Docket Number		TSMC2003-246/1085-191	

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1	JIAN-HSING LEE, J.R. SHIH, Y.H. WU, T.C. ONG, "The Failure Mechanism Of High Voltage Tolerance IO Buffer Under ESD," IEEE 03CH37400. 41st Annual International Reliability Physics Symposium, Dallas, Texas, 2003 (Pages 269-276) © 2003 IEEE.	<input type="checkbox"/>
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